

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT2876487

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
QWAN HO CHUNG	04/23/2014
RECEIVING PARTY DATA	
Name:	SK hynix Inc.
Street Address:	2091, Gyeongchung-daero, Bupal-eub
City:	Icheon
State/Country:	KOREA, REPUBLIC OF
Postal Code:	467-734
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14290572
CORRESPONDENCE DATA	
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Address Line 4:	MOUNTLAKE TERRACE, WASHINGTON 98043
ATTORNEY DOCKET NUMBER:	K100AJ-051400US
NAME OF SUBMITTER:	STEVE Y. CHO
SIGNATURE:	/Steve Y. Cho/
DATE SIGNED:	05/29/2014
Total Attachments: 1	
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ASSIGNMENT OF PATENT APPLICATION

WHEREAS, the below named individual, hereinafter referred to as "ASSIGNOR," is the inventor of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: SEMICONDUCTOR PACKAGE HAVING EMI SHIELDING AND METHOD OF FABRICATING THE SAME

Filing Date: May 29, 2014

Application No.: 14/290,572

WHEREAS, SK hynix Inc., located at 2091, Gyeongchung-daero, Buhul-eub, Icheon-si, Gyeonggi-do, Republic of Korea, hereinafter referred to as "ASSIGNEE," is desirous of acquiring Assignor's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has sold, assigned and transferred, and by these presents do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all right, title and interest in and to the said invention and application including any corresponding foreign application, and in and to any Letters Patent which may hereafter be granted on the same in the United States and any corresponding foreign application, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees that he or she will, without charge to Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the release thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Assignor hereby authorizes and requests AMPAC Law Group, PLLC, 6100 219th Street SW, Suite 580, Mountlake Terrace, WA 98043, to insert herein above the application number and filing date of said application when known.

IN TESTIMONY WHEREOF, Assignor has signed his/her name on the date indicated.

4/23 2014
Date:

Qwan Ho Chung
Name: Qwan Ho CHUNG